


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M24M01E-FMC6TG	CGZW*24M10VA	A	P1C7	25-01-2024
Amount		UoM	Unit type	ST ECOPACK Grade
16.00		mg	Each	ECOPACK® 2
Comment		ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



 life.augmented

Package Designator	Size	Nbr of instances	Shape	
QFN	2x3x0.6	8	No lead	
Comment	Package : ZW UDFPN 2x3x0.6 8L 0.5MM PITCH 7558452			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-14th June 2023				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	CGZW*24M10VA				7000000.0	1000031.5
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.853	mg	supplier	die	Silicon (Si)	7440-21-3		0.805	mg	943728	50313
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	4689	250
				supplier	metallization	Copper (Cu)	7440-50-8		0.014	mg	16413	875
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.002	mg	2345	125
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	2345	125
				supplier	Passivation	Silicon Nitride	12033-89-5		0.004	mg	4689	250
Lead-frame	M-011 Other inorganic materials	2.994	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.022	mg	25791	1375
				supplier	alloy	Copper (Cu)	7440-50-8		2.918	mg	974500	182353
				supplier	alloy	Iron (Fe)	7439-89-6		0.070	mg	23460	4390
				supplier	alloy	Zinc (Zn)	7440-66-6		0.004	mg	1200	225
Lead-frame Coating	M-011 Other inorganic materials	0.013	mg	supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.003	mg	840	157
				supplier	coating	Nickel (Ni)	7440-02-0		0.012	mg	916800	748
				supplier	coating	Palladium (Pd)	7440-05-3		0.001	mg	58700	48
Die Attach	M-011 Other inorganic materials	1.266	mg	supplier	coating	Gold (Au)	7440-57-5		0.000	mg	24500	20
				supplier	glue or soft solder	Silver (Ag)	7440-22-4		1.108	mg	875000	69248
				supplier	glue or soft solder	polymer	28630-26-4		0.101	mg	80000	6331
				supplier	glue or soft solder	aniline	67784-74-1		0.013	mg	10000	791
				supplier	glue or soft solder	epoxy resin	Proprietary		0.038	mg	30000	2374
Wires	M-011 Other inorganic materials	0.036	mg	supplier	glue or soft solder	Epoxy resin molecular weight <= 700	Proprietary		0.006	mg	5000	396
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.036	mg	1000000	2258
Encapsulation	M-011 Other inorganic materials	10.838	mg	supplier	Moulding Compound	vitrous silica	60676-86-0		9.294	mg	857543	580875
				supplier	Moulding Compound	Phenol resin	Proprietary		0.368	mg	33918	22975
				supplier	Moulding Compound	epoxy resin	Proprietary		0.420	mg	38764	26258
				supplier	Moulding Compound	carbon black	1333-86-4		0.021	mg	1938	1313
				supplier	Moulding Compound	2,2'-(3,3',5,5'-tetramethyl-1,1'-biphenyl)-4,4'	85954-11-6		0.210	mg	19382	13129
				supplier	Moulding Compound	Metal hydroxide	Proprietary		0.525	mg	48455	32822
Finishing	M-011 Other inorganic materials	0.000	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.000	mg	916800	7
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	58700	0
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0